V62C2182048
256K X 8 LOW POWER, LOW VOLTAGE SRAM

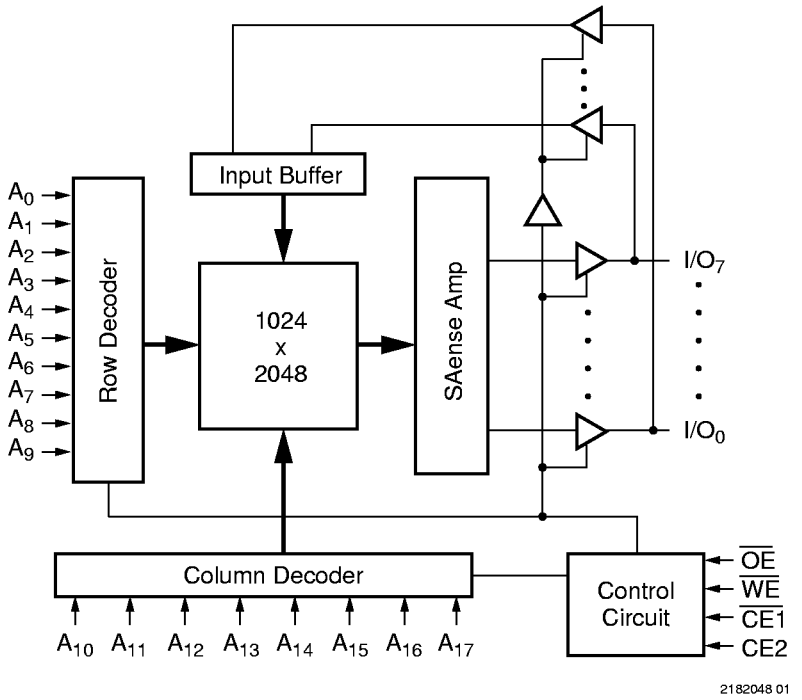
Features

- High-speed: 55, 70 ns
- Ultra low standby current of 2µA (max.)
- Fully static operation
- All inputs and outputs directly compatible
- Three state outputs
- Ultra low data retention current (V_{CC} = 2V)
- Extended operating voltage: 2.3V–3.6V
- Packages
  - 32-Pin TSOP
  - 48-Ball CSP BGA

Description

The V62C2182048 is a very low power CMOS static RAM organized as 131,072 words by 8 bits. Easy memory expansion is provided by an active LOW $\overline{CE1}$, and active HIGH CE2, an active LOW $\overline{OE}$, and three static I/O's. This device has an automatic power-down mode feature when deselected.

Functional Block Diagram



Device Usage Chart

Operating Temperature Range	Package Outline		Access Time (ns)		Power		Temperature Mark
	T	B	55	70	L	LL	
0°C to 70 °C	•	•	•	•	•	•	Blank
–40°C to +85°C	•	•	•	•		•	I

Pin Descriptions

A_0–A_{17} Address Inputs
These 18 address inputs select one of the 256K x 8 bit segments in the RAM.

$\overline{CE}_1$, CE_2 Chip Enable Inputs
$\overline{CE}_1$ is active LOW and CE_2 is active HIGH. Both chip enables must be active to read from or write to the device. If either chip enable is not active, the device is deselected and is in a standby power mode. The I/O pins will be in the high-impedance state when deselected.

$\overline{OE}$ Output Enable Input
The Output Enable input is active LOW. When $\overline{OE}$ is LOW with $\overline{CE}$ LOW and $\overline{WE}$ HIGH, data of the selected memory location will be available on the I/O pins. When $\overline{OE}$ is HIGH, the I/O pins will be in the high impedance state.

$\overline{WE}$ Write Enable Input
An active LOW input, $\overline{WE}$ input controls read and write operations. When $\overline{CE}$ and $\overline{WE}$ inputs are both LOW, the data present on the I/O pins will be written into the selected memory location.

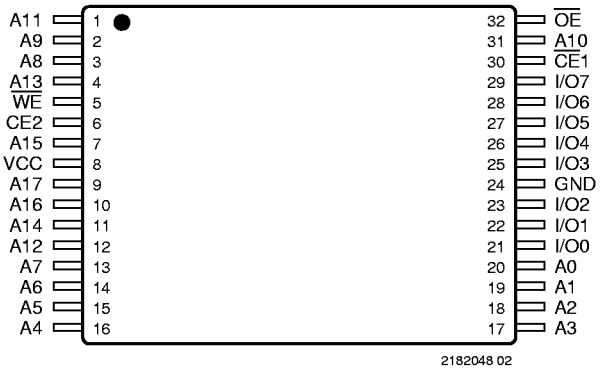
I/O_0–I/O_7 Data Input and Data Output Ports
These 8 bidirectional ports are used to read data from and write data into the RAM.

V_{CC} Power Supply

GND Ground

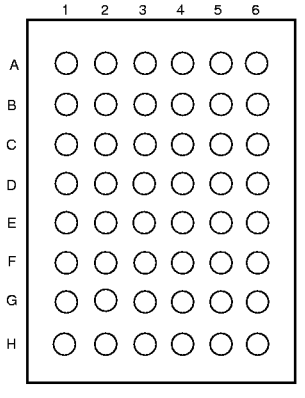
Pin Configurations (Top View)

32-Pin TSOP (Standard)



2182048 02

48 BGA



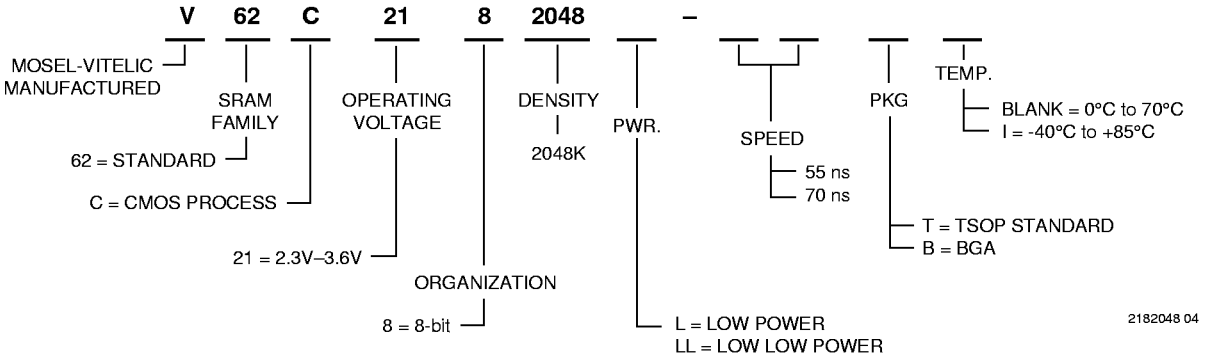
TOP VIEW

	1	2	3	4	5	6
A	A0	A1	CE2	A3	A6	A8
B	I/O4	A2	$\overline{WE}$	A4	A7	I/O0
C	I/O5	NC	NC	A5	NC	I/O1
D	VSS	NC	NC	NC	NC	VCC
E	VCC	NC	NC	NC	NC	VSS
F	I/O6	NC	NC	A17	NC	I/O2
G	I/O7	$\overline{OE}$	$\overline{CE1}$	A16	A15	I/O3
H	A9	A10	A11	A12	A13	A14

Note: NC means no connect. 2182048-03

TOP VIEW

Part Number Information



Absolute Maximum Ratings (1)

Symbol	Parameter	Commercial	Industrial	Units
V_{CC}	Supply Voltage	-0.5 to + V_{CC} + 0.5	-0.5 to + V_{CC} + 0.5	V
V_N	Input Voltage	-0.5 to + V_{CC} + 0.5	-0.5 to + V_{CC} + 0.5	V
V_{DQ}	Input/Output Voltage Applied	V_{CC} + 0.3	V_{CC} + 0.3	V
T_{BIAS}	Temperature Under Bias	-10 to +125	-65 to +135	°C
T_{STG}	Storage Temperature	-55 to +125	-65 to +150	°C

NOTE:
1. Stresses greater than those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

Capacitance*

T_A = 25°C, f = 1.0MHz

Symbol	Parameter	Conditions	Max.	Unit
C_{IN}	Input Capacitance	V_{IN} = 0V	6	pF
C_{OUT}	Output Capacitance	$V_{I/O}$ = 0V	8	pF

NOTE:
1. This parameter is guaranteed and not tested.

Truth Table

Mode	$\overline{CE}_1$	CE_2	$\overline{OE}$	$\overline{WE}$	I/O Operation
Standby	H	X	X	X	High Z
Standby	X	L	X	X	High Z
Output Disable	L	H	H	H	High Z
Read	L	H	L	H	D_{OUT}
Write	L	H	X	L	D_{IN}

NOTE:
X = Don't Care, L = LOW, H = HIGH

DC Electrical Characteristics (over all temperature ranges, V_{CC} = 2.3V–3.6V)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
V_{IL}	Input LOW Voltage[1,2]		-0.5	—	0.4	V
V_{IH}	Input HIGH Voltage[1]		2.2	—	V_{CC}+0.3	V
I_{IL}	Input Leakage Current	V_{CC} = Max, V_{IN} = 0V to V_{CC}	—	—	1	µA
I_{OL}	Output Leakage Current	V_{CC} = Max, $\overline{CE}_1$ = V_{IH}, V_{OUT} = 0V to V_{CC}	—	—	1	µA
V_{OL}	Output LOW Voltage	V_{CC} = Min, I_{OL} = 2mA	—	—	0.4	V
V_{OH}	Output HIGH Voltage	V_{CC} = Min, I_{OH} = -1mA	2.4	—	—	V

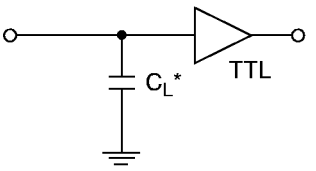
Symbol	Parameter		Comm.	Ind.	Units
I_{CC}	Operating Power Supply Current, $\overline{CE}_1$ = V_{IL}, CE_2 = V_{IH}, Output Open, V_{CC} = Max., f = 0	L	5	6	mA
		LL	4	5	
I_{CC1}	Average Operating Current, $\overline{CE}_1$ = V_{IL}, CE_2 = V_{CC} – 0.2, Output Open, V_{CC} = Max., f = f_{MAX}[3]		50	60	mA
I_{SB}	TTL Standby Current $\overline{CE}_1 \geq V_{IH}$, $CE_2 \leq V_{IL}$, V_{CC} = Max.	L	0.5	1	mA
		LL	0.2	1	
I_{SB1}	CMOS Standby Current, $\overline{CE}_1 \geq V_{CC}$ – 0.2V, $CE_2 \leq$ 0.2V, $V_{IN} \geq V_{CC}$ – 0.2V or $V_{IN} \leq$ 0.2V, V_{CC} = Max.	L	10	20	µA
		LL	2	5	

NOTES:
1. These are absolute values with respect to device ground and all overshoots due to system or tester noise are included.
2. V_{IL} (Min.) = -3.0V for pulse width < $t_{RC}/2$.
3. $f_{MAX} = 1/t_{RC}$.

AC Test Conditions

Input Pulse Levels	0 to 3V
Input Rise and Fall Times	5 ns
Timing Reference Levels	1.4V
Output Load	see below

AC Test Loads and Waveforms



C_L = 30pF + 1TTL Load

* Includes scope and jig capacitance

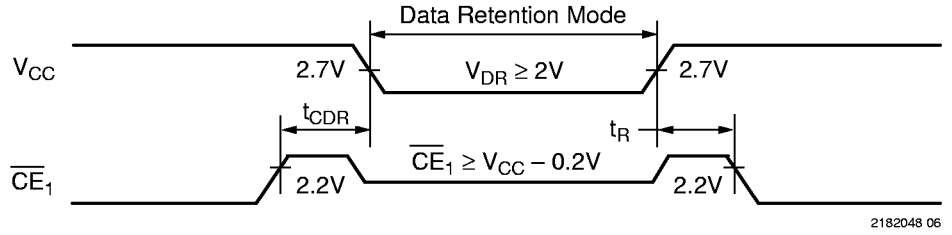
2182048 05

Data Retention Characteristics

Symbol	Parameter		Min.	Max.	Units
V_{DR}	V_{CC} for Data Retention $\overline{CE}_1 \geq V_{CC} - 0.2V$, $CE_2 \leq 0.2V$, $V_{IN} \geq V_{CC} - 0.2V$, or $V_{IN} \leq 0.2V$		2.0	—	V
I_{CCDR}	Data Retention Current $\overline{CE}_1 \geq V_{DR} - 0.2V$, $CE_2 \leq 0.2V$, $V_{IN} \geq V_{CC} - 0.2V$, or $V_{IN} \leq 0.2V$	L	—	2	µA
		LL	—	1	
t_{CDR}	Chip Deselect to Data Retention Time		0	—	ns
t_R	Operation Recovery Time (see Retention Waveform)		t_{RC}(1)	—	ns

NOTES:
1. t_{RC} = Read Cycle Time

Low V_{CC} Data Retention Waveform (1) ($\overline{CE}_1$ Controlled)



Key to Switching Waveforms

WAVEFORM	INPUTS	OUTPUTS
	MUST BE STEADY	WILL BE STEADY
	MAY CHANGE FROM H TO L	WILL BE CHANGING FROM H TO L
	MAY CHANGE FROM L TO H	WILL BE CHANGING FROM L TO H
	DON'T CARE: ANY CHANGE PERMITTED	CHANGING: STATE UNKNOWN
	DOES NOT APPLY	CENTER LINE IS HIGH IMPEDANCE "OFF" STATE

AC Electrical Characteristics

(over all temperature ranges)

Read Cycle

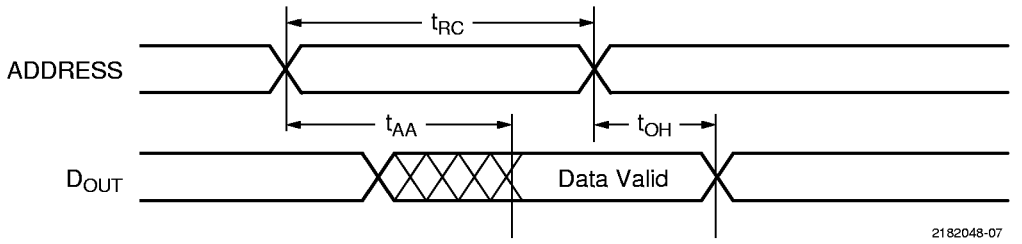
Parameter Name	Parameter	-55		-70		Unit
		Min.	Max.	Min.	Max.	
t_{RC}	Read Cycle Time	55	—	70	—	ns
t_{AA}	Address Access Time	—	55	—	70	ns
t_{ACS1}	Chip Enable Access Time	—	55	—	70	ns
t_{ACS2}	Chip Enable Access Time	—	55	—	70	ns
t_{OE}	Output Enable to Output Valid	—	55	—	40	ns
t_{CLZ1}	Chip Enable to Output in Low Z	10	—	10	—	ns
t_{CLZ2}	Chip Enable to Output in Low Z	10	—	10	—	ns
t_{OLZ}	Output Enable to Output in Low Z	5	—	5	—	ns
t_{CHZ}	Chip Disable to Output in High Z	—	25	—	30	ns
t_{OHZ}	Output Disable to Output in High Z	—	25	—	25	ns
t_{OH}	Output Hold from Address Change	10	—	10	—	ns
t_{PU}	Power Up Time	0	—	0	—	ns
t_{PD}	Power Down Time	—	55	—	70	ns

Write Cycle

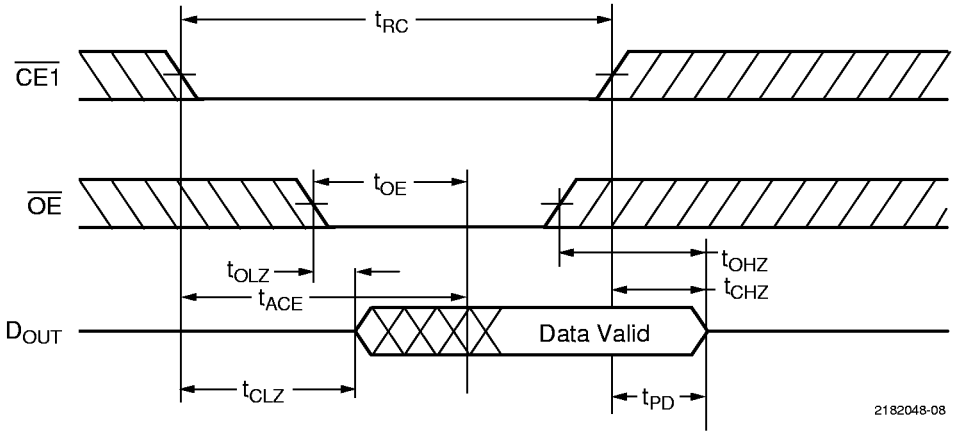
Parameter Name	Parameter	-55		-70		Unit
		Min.	Max.	Min.	Max.	
t_{WC}	Write Cycle Time	55	—	70	—	ns
t_{CW1}	Chip Enable to End of Write	45	—	60	—	ns
t_{CW2}	Chip Enable to End of Write	45	—	60	—	ns
t_{AS}	Address Setup Time	0	—	0	—	ns
t_{AW}	Address Valid to End of Write	45	—	60	—	ns
t_{WP}	Write Pulse Width	45	—	50	—	ns
t_{WR}	Write Recovery Time	5	—	5	—	ns
t_{WHZ}	Write to Output High-Z	—	25	—	30	ns
t_{DW}	Data Setup to End of Write	25	—	30	—	ns
t_{DH}	Data Hold from End of Write	0	—	0	—	ns
t_{OW}	Output Active from End of Write	5	—	5	—	ns
t_{WZ}	Write Enable to Output in High-Z	—	25	—	30	ns

Switching Waveforms (Read Cycle)

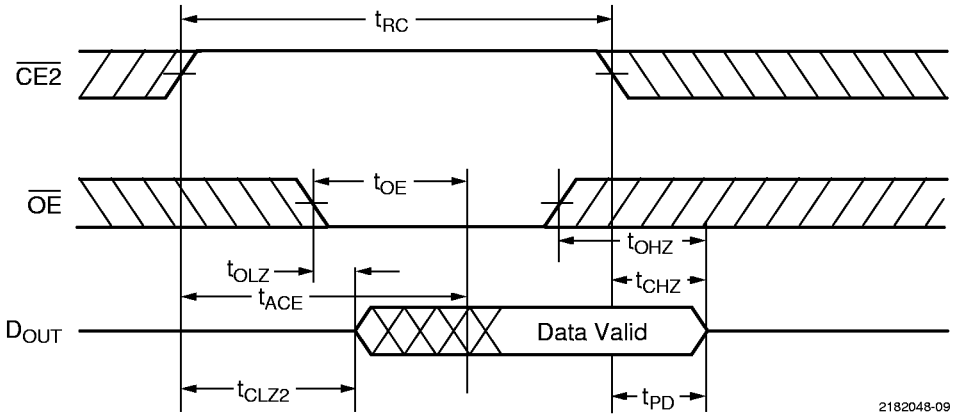
Read Cycle 1 (1, 4, 5, 7)



Read Cycle 2 (1, 4, 6, 7)

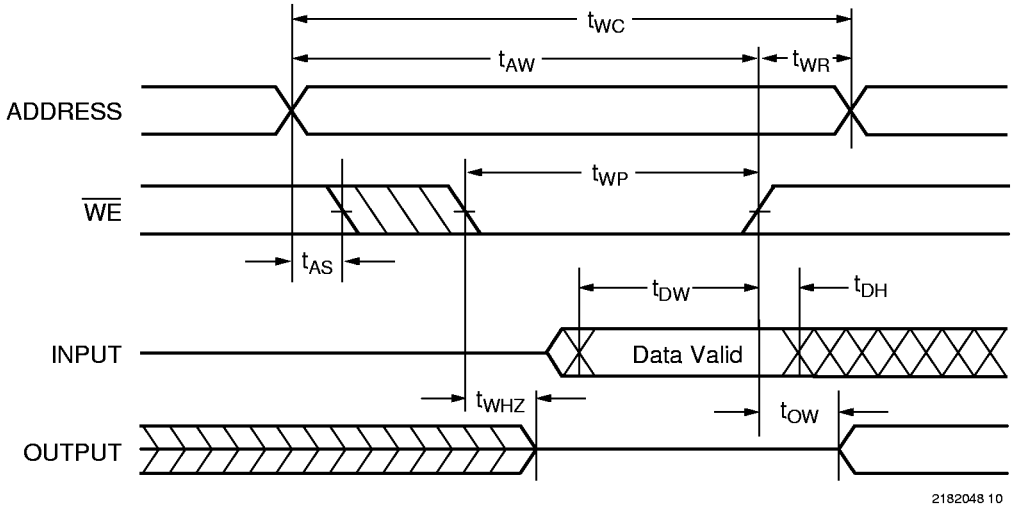


Read Cycle 3 (1, 4, 6, 7)

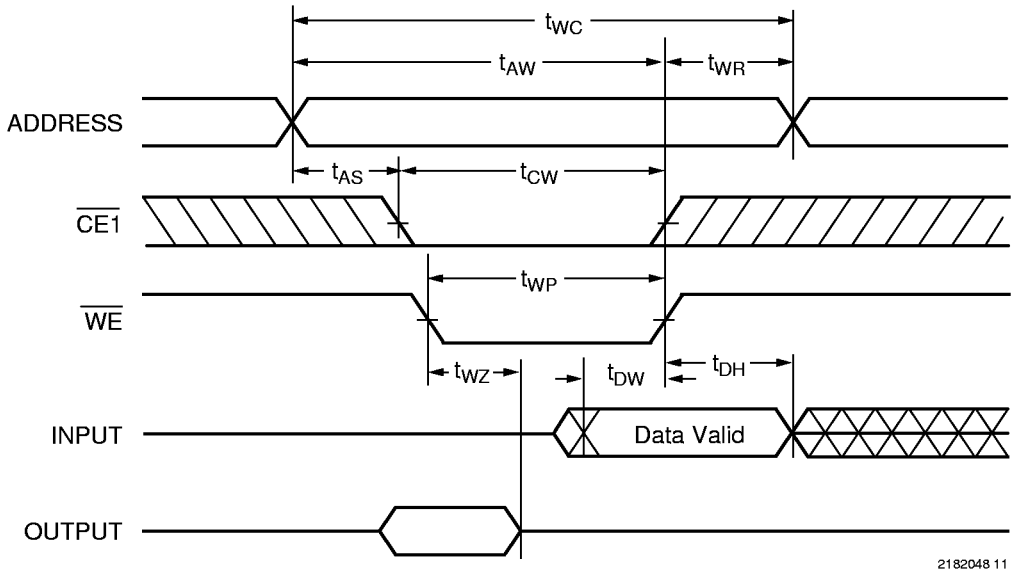


Switching Waveforms (Write Cycle)

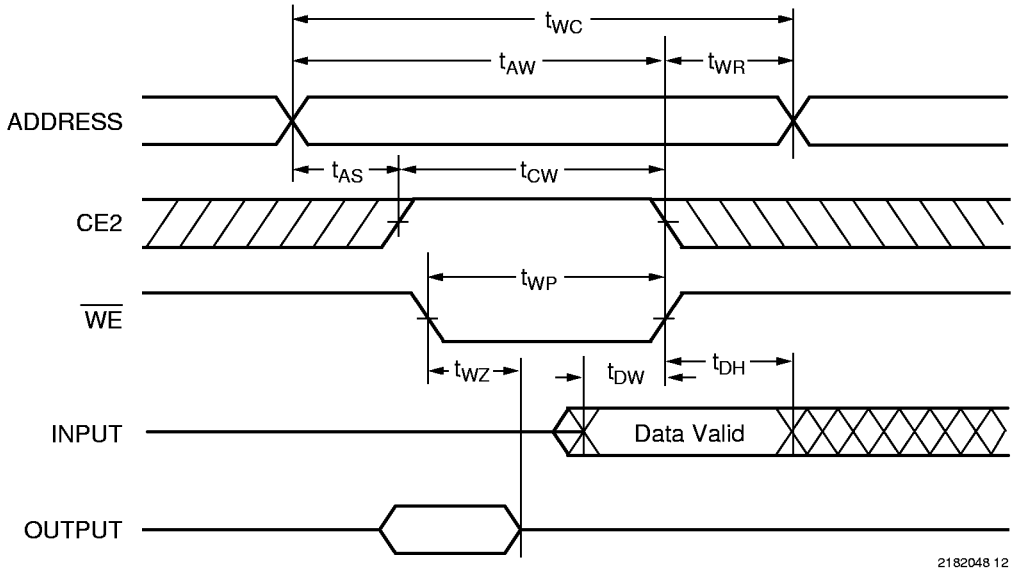
Write Cycle 1 ($\overline{WE}$ Controlled)[8, 9]



Write Cycle 2 ($\overline{CE1}$ Controlled)[8, 9]



Write Cycle 3 (CE2 Controlled) (8, 9)



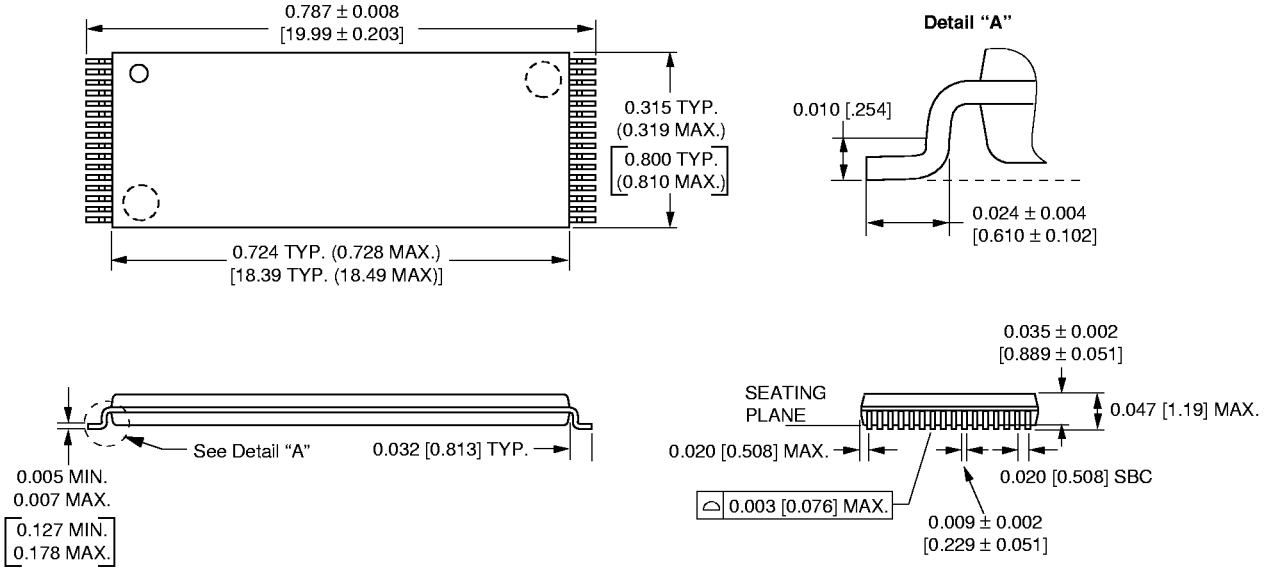
NOTES:

1. The internal write time of the memory is defined by the overlap of $\overline{CE}_1$ and CE_2 active and $\overline{WE}$ low. All signals must be active to initiate and any one signal can terminate a write by going inactive. The data input setup and hold timing should be referenced to the second transition edge of the signal that terminates the write.
2. t_{WR} is measured from the earlier of $\overline{CE}_1$ or $\overline{WE}$ going high, or CE_2 going LOW at the end of the write cycle.
3. During this period, I/O pins are in the output state so that the input signals of opposite phase to the outputs must not be applied.
4. $\overline{OE}$ = V_{IL} or V_{IH}. However it is recommended to keep $\overline{OE}$ at V_{IH} during write cycle to avoid bus contention.
5. If $\overline{CE}_1$ is LOW and CE_2 is HIGH during this period, I/O pins are in the output state. Then the data input signals of opposite phase to the outputs must not be applied to them.
6. t_{CW} is measured from $\overline{CE}_1$ going low or CE_2 going HIGH to the end of write.

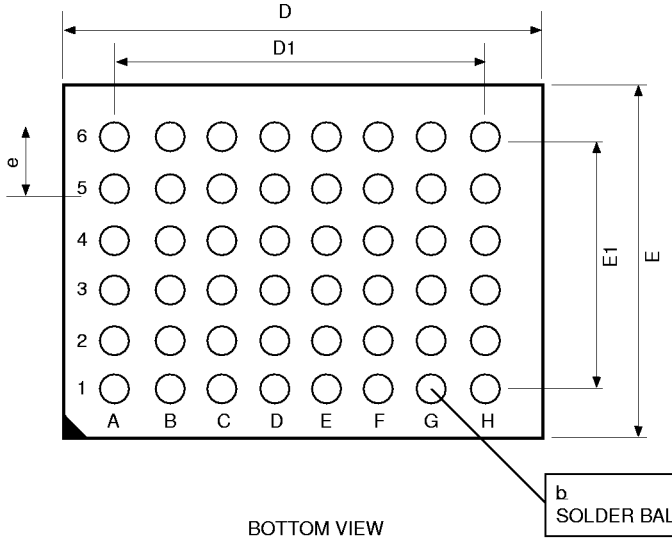
Package Diagrams

32-Pin TSOP (Standard)

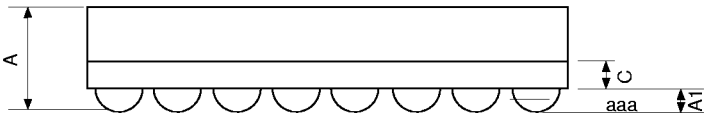
Units in inches [mm]



48 Ball—9x12 fpBGA (Ultra Low Power)



SYMBOL	UNIT.MM
A	1.05+0.15
A1	0.25±0.05
b	0.35±.0.05
c	0.30(TYP)
D	12.00±0.10
D1	5.25
E	9.00±0.10
E1	3.75
e	0.75TYP
aaa	0.10



SIDE VIEW